Quad, Current-Output, Serial-Input 16-/14-Bit DACs

AD5544/AD5554

FEATURES

AD5544 16-bit resolution
AD5554 14-bit resolution
2 mA full-scale current ±20%, with V_{REF} = ±10 V
2 µs settling time
V_{SS} BIAS for zero-scale error reduction @ temp
midscale or zero-scale reset
Four separate, 4-Q multiplying reference inputs
SPI®-compatible 3-wire interface
Double buffered registers enable
Simultaneous multichannel change
Internal power ON reset
Compact SSOP-28 package

APPLICATIONS

Automatic test equipment
Instrumentation
Digitally controlled calibration
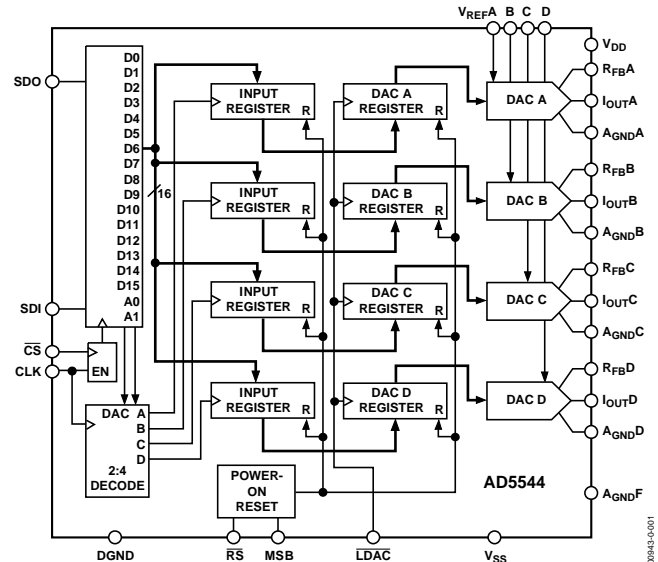
GENERAL DESCRIPTION

The AD5544/AD5554 quad, 16-/14-bit, current-output, digital to-analog converters are designed to operate from a single 5 V supply.

The applied external reference input voltage (V_{REF}) determines the full-scale output current. Integrated feedback resistors (R_{FB}) provide temperature-tracking, full-scale voltage outputs when combined with an external I-to-V precision amplifier.

A double-buffered serial-data interface offers high speed, 3-wire, SPI- and microcontroller-compatible inputs using serial-data-in (SDI), a chip-select ($\overline{CS}$), and clock (CLK) signals. In addition, a serial-data-out pin (SDO) allows for daisy-chaining when multiple packages are used. A common, level-sensitive, load-DAC strobe ($\overline{LDAC}$) input allows the simultaneous update of all DAC outputs from previously loaded input registers. Additionally, an internal power ON reset forces the output voltage to zero at system turn ON. An MSB pin allows system reset assertion ($\overline{RS}$) to force all registers to zero code when MSB = 0, or to half-scale code when MSB = 1.

The AD5544/AD5554 are packaged in the compact SSOP-28.

FUNCTIONAL BLOCK DIAGRAM
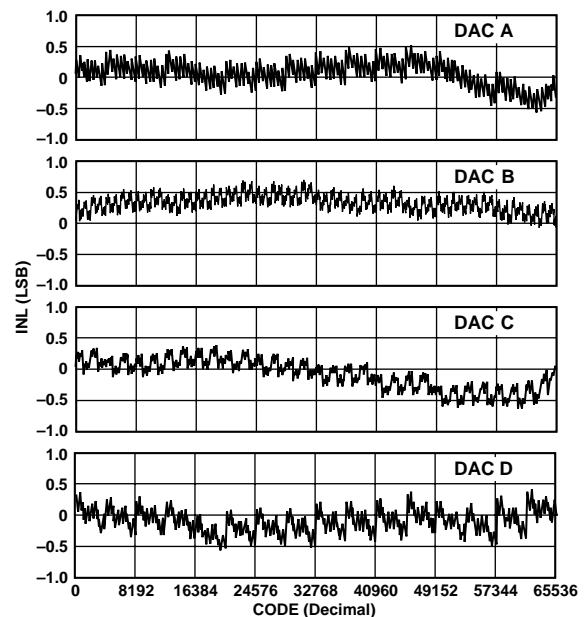
Figure 1.

Figure 2. AD5544 INL vs. Code Plot ($T_A = 25°C$)

AD5554/AD5554

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REVISION HISTORY

12/04—Rev. 0 to Rev. A

4/00—Revision 0: Initial Version

SPECIFICATIONS

AD5544 ELECTRICAL CHARACTERISTICS

V_{DD} = 5 V ±10%, V_{SS} = 0 V, $I_{OUT}X$ = virtual GND, $A_{GND}X$ = 0 V, $V_{REF}A$, B, C, D = 10 V, T_A = full operating temperature range, unless otherwise noted.

Table 1.

Parameter	Symbol	Condition	Min	Typ	Max	Unit
STATIC PERFORMANCE[1]						
Resolution	N	1 LSB = $V_{REF}/2^{16}$ = 153 µV when V_{REF} = 10 V			16	Bits
Relative Accuracy	INL				±4	LSB
Differential Nonlinearity	DNL				±1.5	LSB
Output Leakage Current	$I_{OUT}X$	Data = 0000$_H$, T_A = 25°C			10	nA
	$I_{OUT}X$	Data = 0000$_H$, T_A = T_A max			20	nA
Full-Scale Gain Error	G_{FSE}	Data = FFFF$_H$		±0.75	±3	mV
Full-Scale Tempco[2]	TCV_{FS}			1		ppm/°C
Feedback Resistor	$R_{FB}X$	V_{DD} = 5 V	4	6	8	kΩ
REFERENCE INPUT						
$V_{REF}X$ Range	$V_{REF}X$		−15		+15	V
Input Resistance	$R_{REF}X$		4	6	8	kΩ
Input Resistance Match	$R_{REF}X$	Channel-to-channel		1		%
Input Capacitance[2]	$C_{REF}X$			5		pF
ANALOG OUTPUT						
Output Current	$I_{OUT}X$	Data = FFFF$_H$	1.25		2.5	mA
Output Capacitance[2]	$C_{OUT}X$	Code-dependent		80		pF
LOGIC INPUT AND OUTPUT						
Logic Input Low Voltage	V_{IL}				0.8	V
Logic Input High Voltage	V_{IH}		2.4			V
Input Leakage Current	I_{IL}				1	µA
Input Capacitance[2]	C_{IL}				10	pF
Logic Output Low Voltage	V_{OL}	I_{OL} = 1.6 mA			0.4	V
Logic Output High Voltage	V_{OH}	I_{OH} = 100 µA	4			V
INTERFACE TIMING[2, 3]						
Clock Width High	t_{CH}		25			ns
Clock Width Low	t_{CL}		25			ns
$\overline{CS}$ to Clock Setup	t_{CSS}		0			ns
Clock to $\overline{CS}$ Hold	t_{CSH}		25			ns
Clock to SDO Prop Delay	t_{PD}		2		20	ns
Load DAC Pulse Width	t_{LDAC}		25			ns
Data Setup	t_{DS}		20			ns
Data Hold	t_{DH}		20			ns
Load Setup	t_{LDS}		5			ns
Load Hold	t_{LDH}		25			ns
SUPPLY CHARACTERISTICS						
Power Supply Range	$V_{DD\ RANGE}$		4.5		5.5	V
Positive Supply Current	I_{DD}	Logic inputs = 0 V		50	250	µA
Negative Supply Current	I_{SS}	Logic inputs = 0 V, V_{SS} = −5 V		0.001	1	µA
Power Dissipation	P_{DISS}	Logic inputs = 0 V			1.25	mW
Power Supply Sensitivity	PSS	ΔV_{DD} = ±5%			0.006	%/%

Parameter	Symbol	Condition	Min	Typ	Max	Unit
AC CHARACTERISTICS[4]						
Output Voltage Settling Time	t_S	To ±0.1% of full scale, data = 0000H to FFFF$_H$ to 0x0000		1		µs
Output Voltage Settling Time	t_S	To ±0.0015% of full scale, data = 0000$_H$ to FFFF$_H$ to 0000$_H$		2		µs
Reference Multiplying BW	BW − 3 dB	$V_{REF}X$ = 100 mV rms, data = FFFF$_H$, C_{FB} = 15 pF		2		MHz
DAC Glitch Impulse	Q	$V_{REF}X$ = 10 V, data 0000$_H$ to 8000$_H$ to 0000$_H$		12		nV-s
Feedthrough Error	$V_{OUT}X/V_{REF}X$	Data = 0000$_H$, $V_{REF}X$ = 100 mV rms, f = 100 kHz		−65		dB
Crosstalk Error	$V_{OUT}A/V_{REF}B$	Data = 0000$_H$, $V_{REF}B$ = 100 mV rms, adjacent channel, f = 100 kHz		−90		dB
Digital Feedthrough	Q	$\overline{CS}$ = 1, and f_{CLK} = 1 MHz		5		nV-s
Total Harmonic Distortion	THD	V_{REF} = 5 V p-p, data = FFFF$_H$, f = 1 kHz		−90		dB
Output Spot Noise Voltage	e_N	f = 1 kHz, BW = 1 Hz		7		nV√Hz

[1] All static performance tests (except I_{OUT}) are performed in a closed-loop system using an external precision OP177 I-to-V converter amplifier. The AD5544 R_{FB} terminal is tied to the amplifier output. Typical values represent average readings measured at 25 °C.
[2] These parameters are guaranteed by design and not subject to production testing.
[3] All input control signals are specified with t_R = t_F = 2.5 ns (10% to 90% of 3 V) and timed from a voltage level of 1.5 V.
[4] All ac characteristic tests are performed in a closed-loop system using an OP42 I-to-V converter amplifier.

AD5554 ELECTRICAL CHARACTERISTICS

V_{DD} = 5 V ±10%, V_{SS} = 0 V, $I_{OUT}X$ = virtual GND, $A_{GND}X$ = 0 V, $V_{REF}A$, B, C, D = 10 V, T_A = full operating temperature range, unless otherwise noted.

Table 2.

Parameter	Symbol	Condition	Min	Typ	Max	Unit
STATIC PERFORMANCE[1]						
Resolution	N	1 LSB = $V_{REF}/2^{14}$ = 610 µV when V_{REF} = 10 V			14	Bits
Relative Accuracy	INL				±1	LSB
Differential Nonlinearity	DNL				±1	LSB
Output Leakage Current	$I_{OUT}X$	Data = 0000$_H$, T_A = 25°C			10	nA
	$I_{OUT}X$	Data = 0000$_H$, T_A = T_A Max			20	nA
Full-Scale Gain Error	G_{FSE}	Data = 3FFF$_H$		±2	±10	mV
Full-Scale Tempco[2]	TCV_{FS}			1		ppm/°C
Feedback Resistor	$R_{FB}X$	V_{DD} = 5 V	4	6	8	kΩ
REFERENCE INPUT						
$V_{REF}X$ Range	$V_{REF}X$		−15		+15	V
Input Resistance	$R_{REF}X$		4	6	8	kΩ
Input Resistance Match	$R_{REF}X$	Channel-to-channel		1		%
Input Capacitance[2]	$C_{REF}X$			5		pF
ANALOG OUTPUT						
Output Current	$I_{OUT}X$	Data = 3FFF$_H$	1.25		2.5	mA
Output Capacitance[2]	$C_{OUT}X$	Code-dependent		80		pF
LOGIC INPUT AND OUTPUT						
Logic Input Low Voltage	V_{IL}				0.8	V
Logic Input High Voltage	V_{IH}		2.4			V
Input Leakage Current	I_{IL}				1	µA
Input Capacitance[2]	C_{IL}				10	pF
Logic Output Low Voltage	V_{OL}	I_{OL} = 1.6 mA			0.4	V
Logic Output High Voltage	V_{OH}	I_{OH} = 100 µA	4			V

Parameter	Symbol	Condition	Min	Typ	Max	Unit
INTERFACE TIMING[2, 3]						
Clock Width High	t_{CH}		25			ns
Clock Width Low	t_{CL}		25			ns
$\overline{CS}$ to Clock Setup	t_{CSS}		0			ns
Clock to $\overline{CS}$ Hold	t_{CSH}		25			ns
Clock to SDO Prop Delay	t_{PD}		2		20	ns
Load DAC Pulse Width	t_{LDAC}		25			ns
Data Setup	t_{DS}		20			ns
Data Hold	t_{DH}		20			ns
Load Setup	t_{LDS}		5			ns
Load Hold	t_{LDH}		25			ns
SUPPLY CHARACTERISTICS						
Power Supply Range	$V_{DD\ RANGE}$		4.5		5.5	V
Positive Supply Current	I_{DD}	Logic inputs = 0 V		50	250	μA
Negative Supply Current	I_{SS}	Logic inputs = 0 V, V_{SS} = −5 V		0.001	1	μA
Power Dissipation	P_{DISS}	Logic inputs = 0 V			1.25	mW
Power Supply Sensitivity	PSS	ΔV_{DD} = ±5%			0.006	%/%
AC CHARACTERISTICS[4]						
Output Voltage Settling Time	t_S	To ±0.1% of full scale, data = 0000$_H$ to 3FFF$_H$ to 0000$_H$		1		μs
Output Voltage Settling Time	t_S	To ±0.0015% of full scale, data = 0000$_H$ to 3FFF$_H$ to 0000$_H$		2		μs
Reference Multiplying BW	BW − 3 dB	$V_{REF}X$ = 100 mV rms, data = 3FFF$_H$, C_{FB} = 15 pF		2		MHz
DAC Glitch Impulse	Q	$V_{REF}X$ = 10 V, data 0000$_H$ to 2000$_H$ to 0000$_H$		12		nV-s
Feedthrough Error	$V_{OUT}X/V_{REF}X$	Data = 0000$_H$, $V_{REF}X$ = 100 mV rms, f = 100 kHz		−65		dB
Crosstalk Error	$V_{OUT}A/V_{REF}B$	Data = 0000$_H$, $V_{REF}B$ = 100 mV rms, adjacent channel, f = 100 kHz		−90		dB
Digital Feedthrough	Q	$\overline{CS}$ = 1, and f_{CLK} = 1 MHz			5	nV-s
Total Harmonic Distortion	THD	V_{REF} = 5 V p-p, data = 3FFF$_H$, f = 1 kHz		−90		dB
Output Spot Noise Voltage	e_N	f = 1 kHz, BW = 1 Hz		7		nV√Hz

[1] All static performance tests (except I_{OUT}) are performed in a closed-loop system using an external precision OP177 I-to-V converter amplifier. The AD5554 R_{FB} terminal is tied to the amplifier output. Typical values represent average readings measured at 25°C.
[2] These parameters are guaranteed by design and not subject to production testing.
[3] All input control signals are specified with $t_R = t_F$ = 2.5 ns (10% to 90% of 3 V) and timed from a voltage level of 1.5 V.
[4] All ac characteristic tests are performed in a closed-loop system using an OP42 I-to-V converter amplifier.

ABSOLUTE MAXIMUM RATINGS

Table 3.

Parameter	Rating
V_{DD} to GND	−0.3 V, +8 V
V_{SS} to GND	+0.3 V, −7 V
V_{REF} to GND	−18 V, +18 V
Logic Input and Output to GND	−0.3 V, +8 V
$V(I_{OUT})$ to GND	−0.3 V, V_{DD}+ 0.3 V
$A_{GND}X$ to DGND	−0.3 V, + 0.3 V
Input Current to Any Pin Except Supplies	±50 mA
Package Power Dissipation	$(T_J$ Max − $T_A)/\theta_{JA}$
Thermal Resistance	θ_{JA}
28-Lead Shrink Surface-Mount (RS-28)	100°C/W
Maximum Junction Temperature (T_J Max)	150°C
Operating Temperature Range: Model A	−40°C to +85°C
Storage Temperature Range	−65°C to +150°C
Lead Temperature:	
RS-28 (Vapor Phase, 60 secs)	215°C
RS-28 (Infrared, 15 secs)	220°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although this product features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.
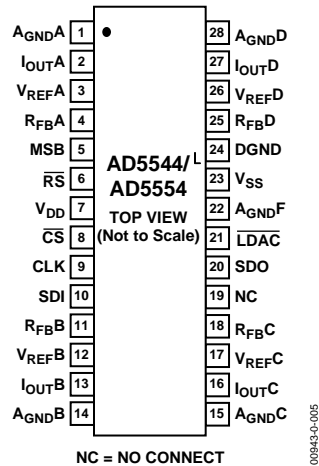
PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

```
        A_GND A  1  ●           28  A_GND D
        I_OUT A  2              27  I_OUT D
        V_REF A  3              26  V_REF D
        R_FB A   4              25  R_FB D
        MSB      5   AD5544/ᴸ   24  DGND
        RS̄       6   AD5554     23  V_SS
        V_DD     7  TOP VIEW    22  A_GND F
        CS̄       8  (Not to Scale) 21  LDAC̄
        CLK      9              20  SDO
        SDI      10             19  NC
        R_FB B   11             18  R_FB C
        V_REF B  12             17  V_REF C
        I_OUT B  13             16  I_OUT C
        A_GND B  14             15  A_GND C

              NC = NO CONNECT
```

Figure 3. AD5544/AD5554 Pin Configuration

Table 4. Pin Function Descriptions

Pin No.	Name	Function
1	$A_{GND}A$	DAC A Analog Ground.
2	$I_{OUT}A$	DAC A Current Output.
3	$V_{REF}A$	DAC A Reference Voltage Input Terminal. Establishes DAC A full-scale output voltage. Pin can be tied to V_{DD} pin.
4	$R_{FB}A$	Establish voltage output for DAC A by connecting to external amplifier output.
5	MSB	MSB Bit. Set pin during a reset pulse ($\overline{RS}$) or at system power ON if tied to ground or V_{DD}.
6	$\overline{RS}$	Reset Pin, Active Low Input. Input registers and DAC registers are set to all zeros or half-scale code (8000$_H$ for AD5544 and 2000$_H$ for AD5554) determined by the voltage on the MSB pin. Register Data = 0000$_H$ when MSB = 0. Register Data = 8000$_H$ for AD5544 and 2000$_H$.
7	V_{DD}	Positive Power Supply Input. Specified range of operation 5 V ±10%.
8	$\overline{CS}$	Chip Select, Active Low Input. Disables shift register loading when high. Transfers serial register data to the input register when $\overline{CS}$/LDAC returns high. Does not effect $\overline{LDAC}$ operation.
9	CLK	Clock Input. Positive edge clocks data into shift register.
10	SDI	Serial Data Input. Input data loads directly into the shift register.
11	$R_{FB}B$	Establish voltage output for DAC B by connecting to external amplifier output.
12	$V_{REF}B$	DAC B Reference Voltage Input Terminal. Establishes DAC B full-scale output voltage. Pin can be tied to V_{DD} pin.
13	$I_{OUT}B$	DAC B Current Output.
14	$A_{GND}B$	DAC B Analog Ground.
15	$A_{GND}C$	DAC C Analog Ground.
16	$I_{OUT}C$	DAC C Current Output.
17	$V_{REF}C$	DAC C Reference Voltage Input Terminal. Establishes DAC C full-scale output voltage. Pin can be tied to V_{DD} pin.
18	$R_{FB}C$	Establish voltage output for DAC C by connecting to external amplifier output.
19	NC	No Connect. Leave pin unconnected.
20	SDO	Serial Data Output. Input data loads directly into the shift register. Data appears at SDO, 19 clock pulses for AD5544 and 17 clock pulses for AD5554 after input at the SDI pin.
21	$\overline{LDAC}$	Load DAC Register Strobe, Level Sensitive Active Low. Transfers all input register data to DAC registers. Asynchronous active low input. See Table 5 and Table 6 for operation.
22	AGNDF	High Current Analog Force Ground.
23	VSS	Negative Bias Power Supply Input. Specified range of operation: −5.5 V to +0.3 V.
24	DGND	Digital Ground Pin.
25	$R_{FB}D$	Establish Voltage Output for DAC D by Connecting to External Amplifier Output.
26	$V_{REF}D$	DAC D Reference Voltage Input Terminal. Establishes DAC D full-scale output voltage. Pin can be tied to V_{DD} pin.
27	$I_{OUT}D$	DAC D Current Output.
28	$A_{GND}D$	DAC D Analog Ground.
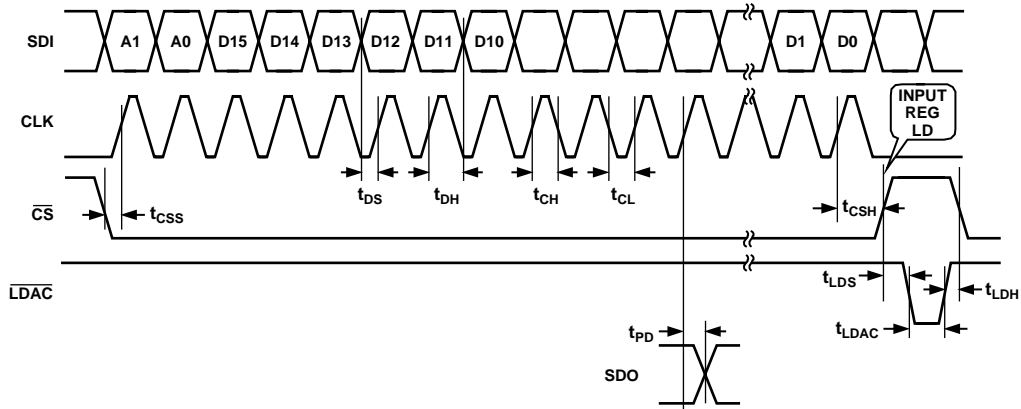
Figure 4. AD5544 Timing Diagram
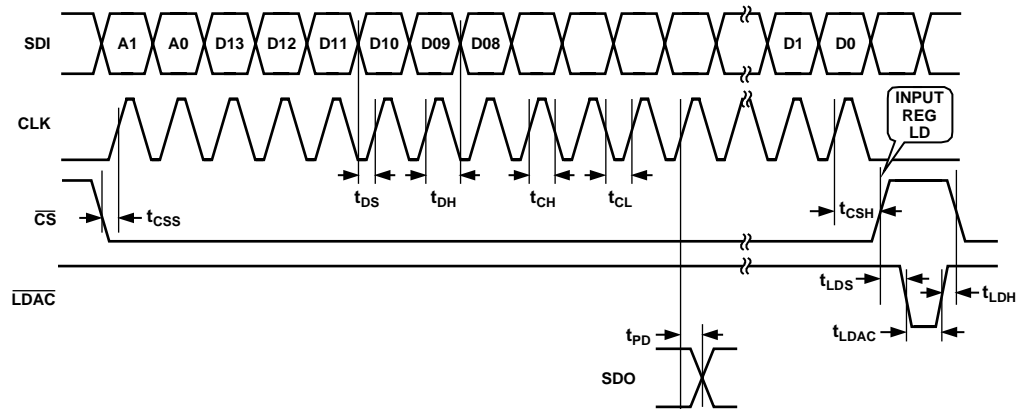
Figure 5. AD5554 Timing Diagram

Table 5. AD5544[1] Control-Logic Truth Table

$\overline{CS}$	CLK	$\overline{LDAC}$	$\overline{RS}$	MSB	Serial Shift Register Function	Input Register Function	DAC Register
H	X	H	H	X	No Effect	Latched	Latched
L	L	H	H	X	No Effect	Latched	Latched
L	↑+	H	H	X	Shift-Register-Data Advanced One Bit	Latched	Latched
L	H	H	H	X	No Effect	Latched	Latched
↑+	L	H	H	X	No Effect	Selected DAC Updated with Current SR Contents	Latched
H	X	L	H	X	No Effect	Latched	Transparent
H	X	H	H	X	No Effect	Latched	Latched
H	X	↑+	H	X	No Effect	Latched	Latched
H	X	H	L	0	No Effect	Latched Data = 0000$_H$	Latched Data = 0000$_H$
H	X	H	L	H	No Effect	Latched Data = 8000$_H$	Latched Data = 8000$_H$

[1] For the AD5544, data appears at the SDO Pin 19 clock pulses after input at the SDI pin.

Table 6. AD5554[1] Control-Logic Truth Table

CS̄	CLK	LDAC̄	RS̄	MSB	Serial Shift Register[2] Function	Input Register[2] Function	DAC Register
H	X	H	H	X[3]	No Effect	Latched	Latched
L	L	H	H	X	No Effect	Latched	Latched
L	↑+[2]	H	H	X	Shift-Register-Data Advanced One Bit	Latched	Latched
L	H	H	H	X	No Effect	Latched	Latched
↑+[2]	L	H	H	X	No Effect	Selected DAC Updated with Current Shift-Register Contents[4]	Latched
H	X	L	H	X	No Effect	Latched	Transparent
H	X	H	H	X	No Effect	Latched	Latched
H	X	↑+	H	X	No Effect	Latched	Latched
H	X	H	L	0	No Effect	Latched Data = 0000$_H$	Latched Data = 0000$_H$
H	X	H	L	H	No Effect	Latched Data = 2000$_H$	Latched Data = 2000$_H$

[1] For the AD5554, data appears at the SDO Pin 17 clock pulses after input at the SDI pin.
[2] ↑+ positive logic transition.
[3] X = don't care.
[4] At power on both the input register and the DAC register are loaded with all zeros.

Table 7. AD5544 Serial Input Register Data Format, Data Is Loaded in the MSB-First Format[1]

	MSB																	LSB
Bit Position	B17	B16	B15	B14	B13	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1	B0
Data Word	A1	A0	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0

[1] Only the last 18 bits of data clocked into the serial register (address + data) are inspected when the CS̄ line's positive edge returns to logic high. At this point an internally generated load strobe transfers the serial register data contents (Bits D15 to D0) to the decoded DAC-input-register address determined by Bits A1 and A0. Any extra bits clocked into the AD5544 shift register are ignored; only the last 18 bits clocked in are used. If double-buffered data is not needed, the LDAC̄ pin can be tied logic low to disable the DAC registers.

Table 8. AD5554 Serial Input Register Data Format, Data Is Loaded in the MSB-First Format[1]

	MSB															LSB
Bit Position	B15	B14	B13	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1	B0
Data Word	A1	A0	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0

[1] Only the last 16 bits of data clocked into the serial register (address + data) are inspected when the CS̄ line's positive edge returns to logic high. At this point an internally generated load strobe transfers the serial register data contents (Bits D13 to D0) to the decoded DAC-input-register address determined by Bits A1 and A0. Any extra bits clocked into the AD5554 shift register are ignored; only the last 16 bits clocked in are used. If double-buffered data is not needed, the LDAC̄ pin can be tied logic low to disable the DAC registers.

Table 9. Address Decode

A1	A0	DAC Decoded
0	0	DAC A
0	1	DAC B
1	0	DAC C
1	1	DAC D

TYPICAL PERFORMANCE CHARACTERISTICS
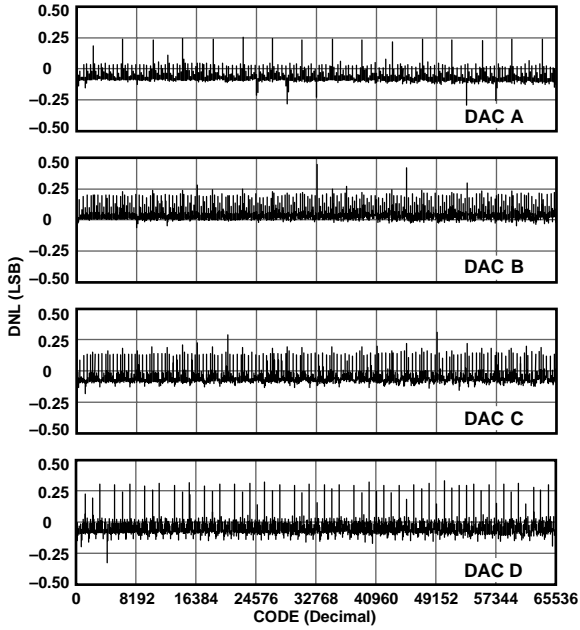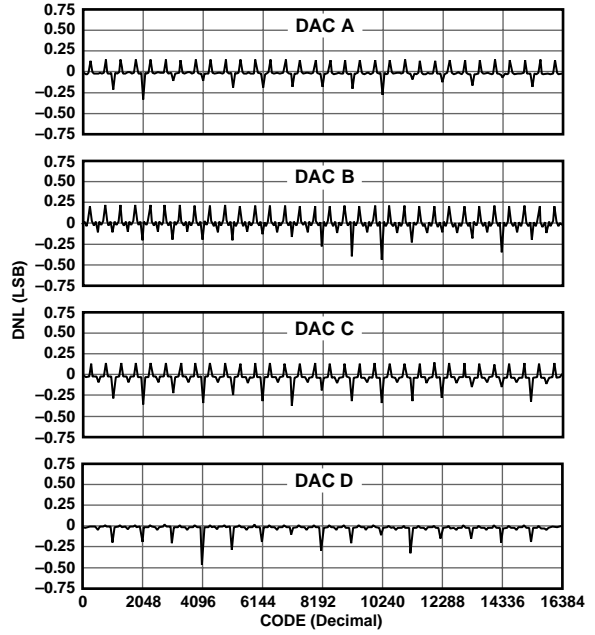

Figure 6. AD5544 DNL vs. Code, $T_A = 25°C$

Figure 7. AD5554 INL vs. Code, $T_A = 25°C$

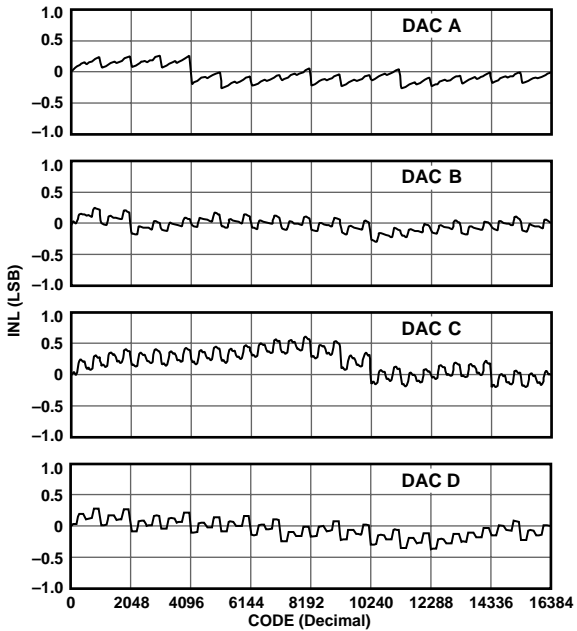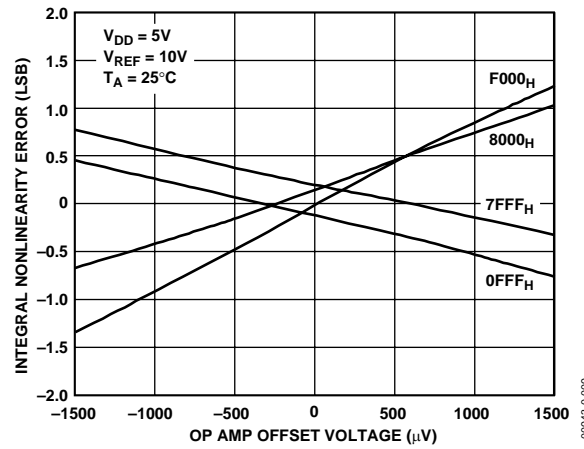

Figure 8. AD5554 DNL vs. Code, $T_A = 25°C$

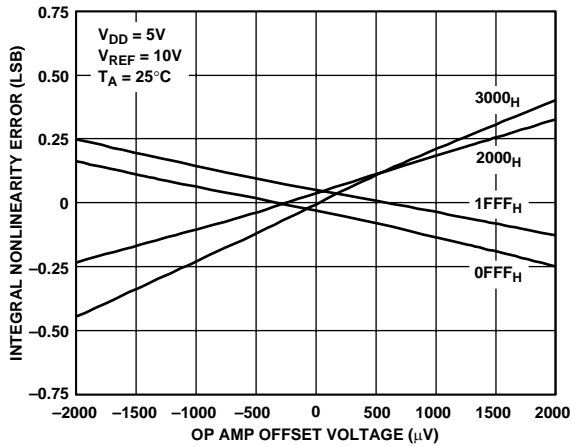Figure 9. AD5544 Integral Nonlinearity Error vs. Op Amp Offset

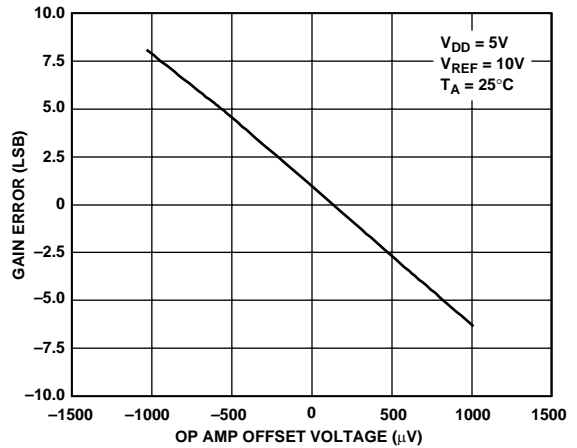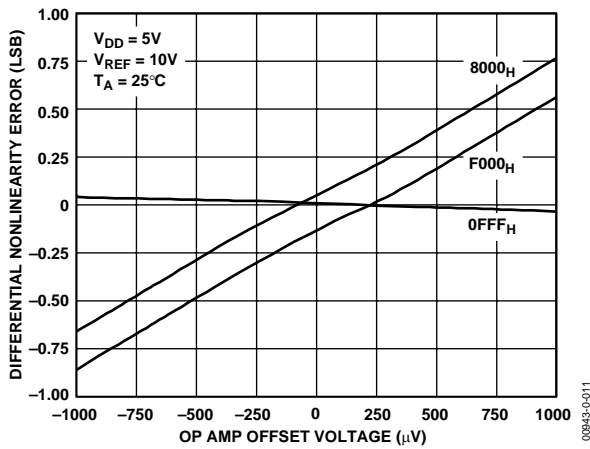Figure 10. AD5554 Integral Nonlinearity Error vs. Op Amp Offset

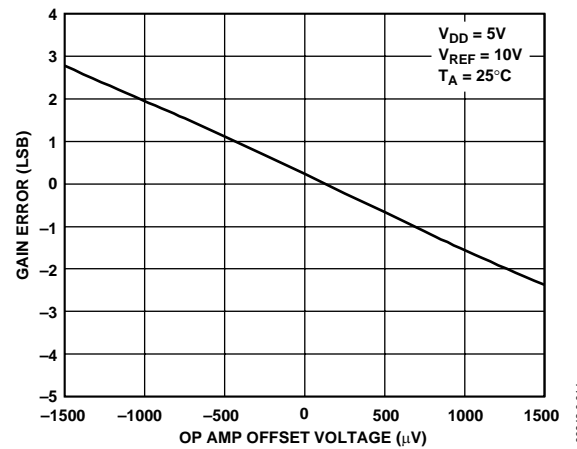Figure 11. AD5544 Differential Nonlinearity Error vs. Op Amp Offset
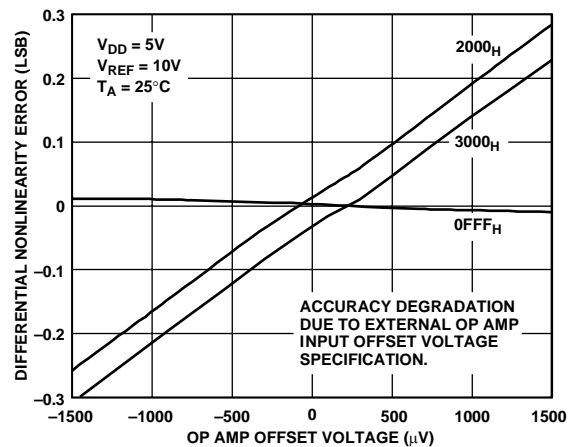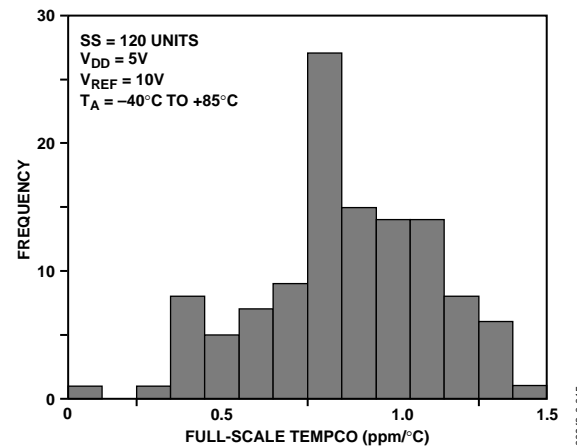

Figure 12. AD5554 Differential Nonlinearity Error vs. Op Amp Offset

Figure 13. AD5544 Gain Error vs. Op Amp Offset

Figure 14. AD5554 Gain Error vs. Op Amp Offset

Figure 15. AD5544 Full-Scale Tempco (ppm/°C)
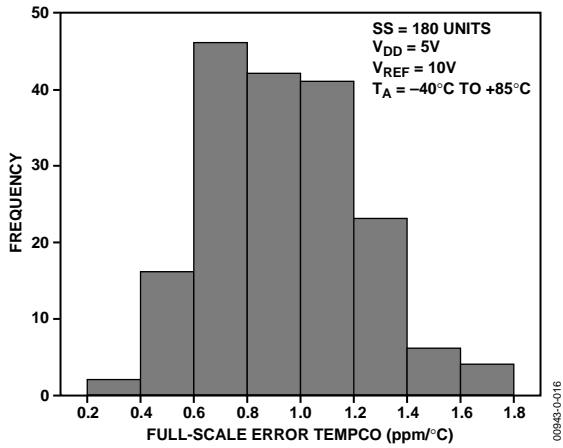
Figure 16. AD5554 Full-Scale Tempco (ppm/°C)
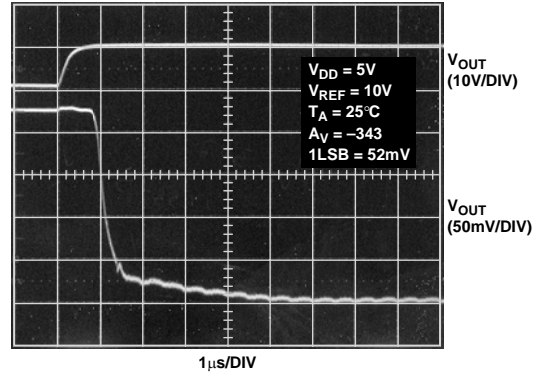
Figure 19. AD5544 Small Signal Settling Time
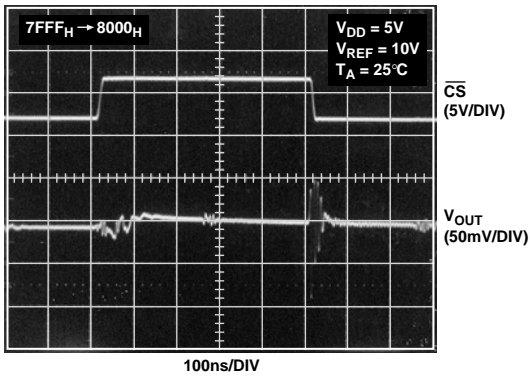
Figure 17. AD5544 Midscale Transition
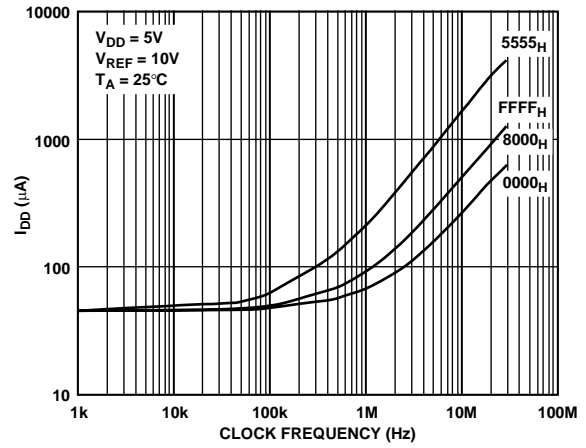
Figure 20. AD5544 Power Supply Current vs. Clock Frequency
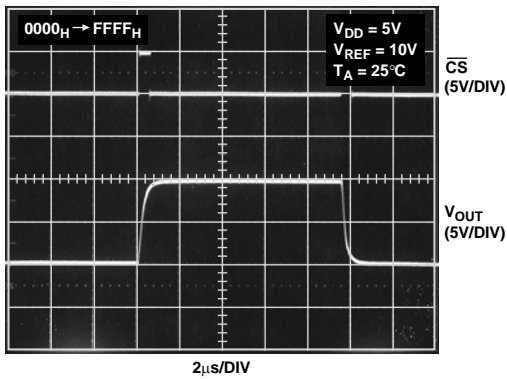
Figure 18. AD5544 Large Signal Settling Time
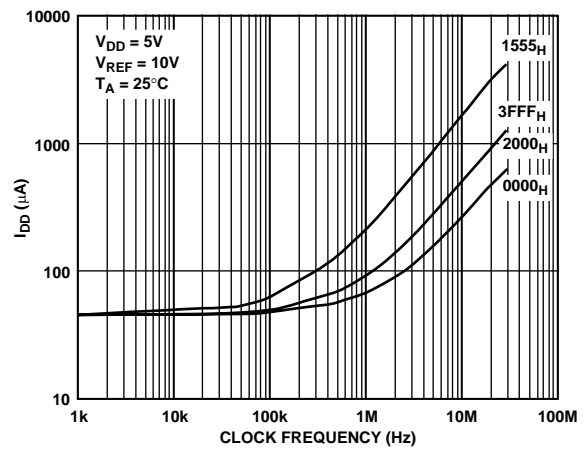
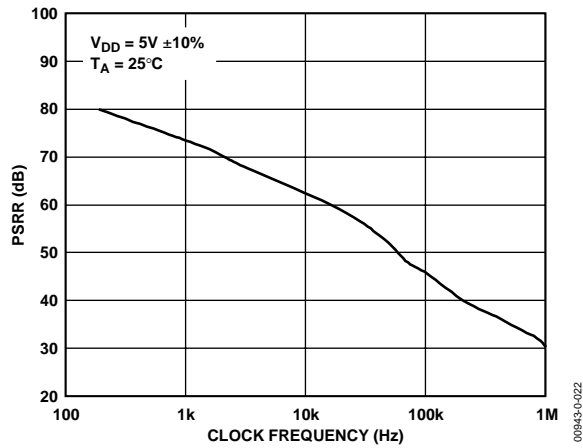Figure 21. AD5554 Power Supply Current vs. Clock Frequency

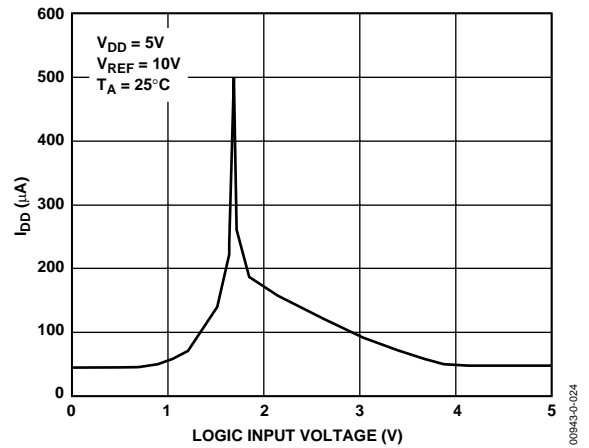Figure 22. AD5544/AD5554 Power Supply Rejection vs. Frequency

Figure 24. AD5544/AD5554 Power Supply Current vs. Logic Input Voltage
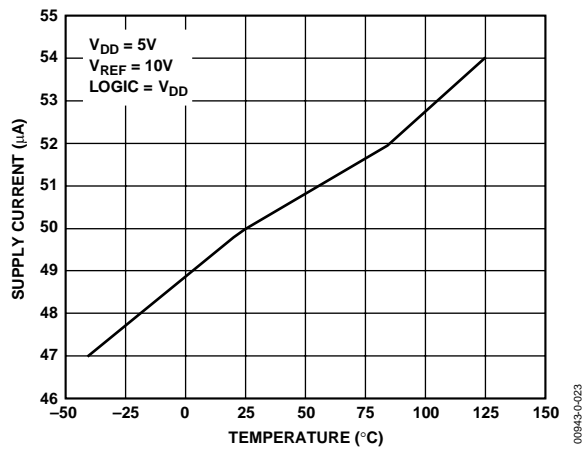

Figure 23. AD5544/AD5554 Power Supply Current vs. Temperature

CIRCUIT OPERATION

The AD5544 and AD5554 contain four, 16-bit and 14-bit, current-output, digital-to-analog converters, respectively. Each DAC has its own independent multiplying reference input. Both the AD5544 and the AD5554 use a 3-wire, SPI compatible, serial data interface, with a configurable asynchronous $\overline{RS}$ pin for half-scale (MSB = 1) or zero-scale (MSB = 0) preset. In addition, an $\overline{LDAC}$ strobe enables four channel simultaneous updates for hardware synchronized output voltage changes.

D/A CONVERTER

Each part contains four current-steering R-2R ladder DACs. Figure 25 shows a typical equivalent DAC. Each DAC contains a matching feedback resistor for use with an external I-to-V converter amplifier. The $R_{FB}X$ pin connects to the output of the external amplifier. The $I_{OUT}X$ terminal connects to the inverting input of the external amplifier. The $A_{GND}X$ pin should be Kelvin-connected to the load point requiring full 16-bit accuracy. These DACs are designed to operate with both negative or positive reference voltage. The V_{DD} power pin is only used by the logic to drive the DAC switches on and off. Note that a matching switch is used in series with the internal 5 kΩ feedback resistor. If users attempt to measure the value of R_{FB}, power must be applied to V_{DD} in order to achieve continuity. An additional VSS bias pin is used to guard the substrate during high temperature applications, minimizing zero-scale leakage currents that double every 10°C. The DAC output voltage is determined by V_{REF} and the digital data (D) in the following equations:

$$V_{OUT} = -V_{REF} \times \frac{D}{65536} \left(For\ AD5544 \right) \quad (1)$$

$$V_{OUT} = -V_{REF} \times \frac{D}{16384} \left(For\ AD5554 \right) \quad (2)$$

Note that the output polarity is opposite to the V_{REF} polarity for dc reference voltages.
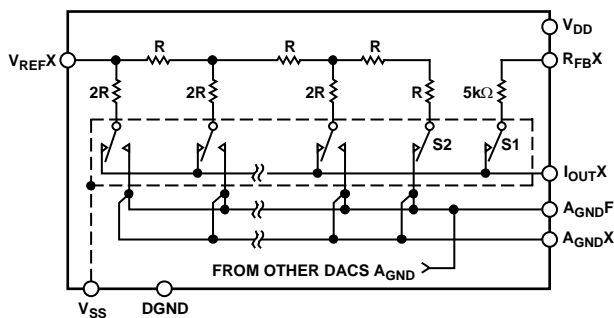
DIGITAL INTERFACE CONNECTIONS OMITTED FOR CLARITY.
SWITCHES S1 AND S2 ARE CLOSED, V_{DD} MUST BE POWERED.

Figure 25. Typical Equivalent DAC Channel

These DACs are also designed to accommodate ac reference input signals. Both the AD5544 and the AD5554 accommodate input reference voltages in the range of −12 V to +12 V. The reference voltage inputs exhibit a constant nominal input

resistance of 5 kΩ, ±30%. On the other hand, the DAC outputs IOUTA, B, C, D are code-dependent and produce various output resistances and capacitances. The choice of external amplifier should take into account the variation in impedance generated by the AD5544/AD5554 on the amplifiers' inverting input node. The feedback resistance, in parallel with the DAC ladder resistance, dominates output voltage noise. For multiplying mode applications, an external feedback compensation capacitor (C_{FB}) may be needed to provide a critically damped output response for step changes in reference input voltages. Figure 26 and Figure 27 show the gain vs. frequency performance at various attenuation settings using a 23 pF external feedback capacitor connected across the $I_{OUT}X$ and $R_{FB}X$ terminals for AD5544 and AD5554, respectively. In order to maintain good analog performance, power supply bypassing of 0.01 μF, in parallel with 1 μF, is recommended. Under these conditions, a clean power supply with low ripple voltage capability should be used. Switching power supplies is usually not suitable for this application due to the higher ripple voltage and PSS frequency-dependent characteristics. It is best to derive the AD5544/AD5554's 5 V supply from the system's analog supply voltages. Do not use the digital 5 V supply (see Figure 28).
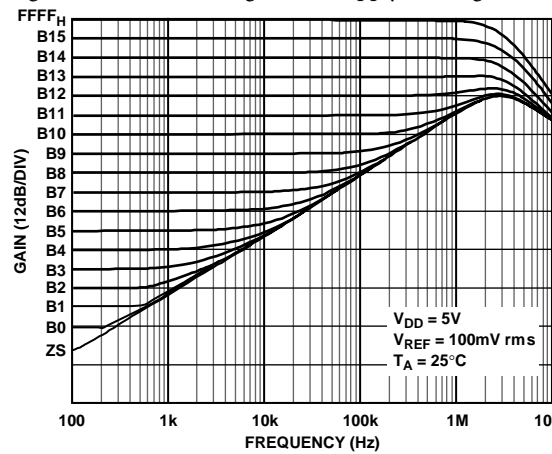

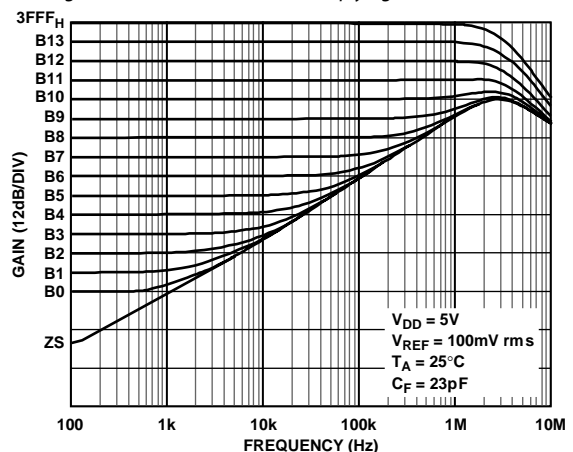Figure 26. AD5554 Reference Multiplying Bandwidth vs. Code

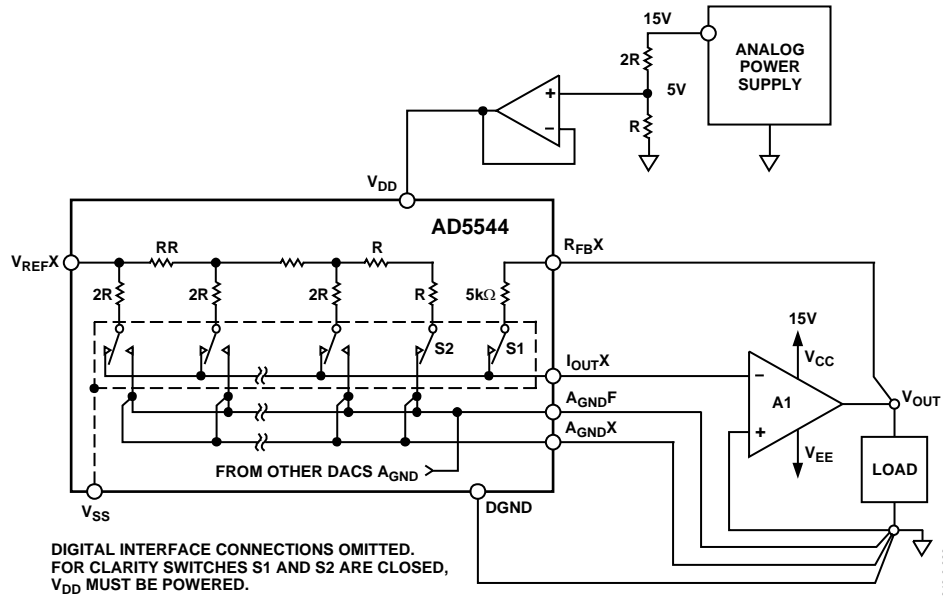Figure 27. AD5554 Reference Multiplying Bandwidth vs. Code

Figure 28. Recommended Kelvin-Sensed Hookup

SERIAL DATA INTERFACE

The AD5544/AD5554 uses a 3-wire ($\overline{CS}$, SDI, CLK) SPI compatible serial data interface. Serial data of AD5544 and AD5554 is clocked into the serial input register in an 18-bit and 16-bit data-word format respectively. MSB bits are loaded first. Table 6 defines the 18 data-word bits for AD5544.

Table 7 defines the 16 data-word bits for AD5554. Data is placed on the SDI pin, and clocked into the register on the positive clock edge of CLK subject to the data setup and data hold time requirements specified in the interface timing specifications. data can only be clocked in while the $\overline{CS}$ chip select pin is active low. For AD5544, only the last 18 bits clocked into the serial register will be interrogated when the $\overline{CS}$ pin returns to the logic high state, extra data bits are ignored. For AD5554, only the last 16 bits clocked into the serial register will be interrogated when the $\overline{CS}$ pin returns to the logic high state. Since most microcontrollers output serial data in 8-bit bytes, three right justified data bytes can be written to the AD5544. Keeping

the $\overline{CS}$ line low between the first, second, and third byte transfers will result in a successful serial register update. Similarly, two right justified data bytes can be written to the AD5554. Keeping the $\overline{CS}$ line low between the first and second byte transfer will result in a successful serial register update.

Once the data is properly aligned in the shift register, the positive edge of the $\overline{CS}$ initiates the transfer of new data to the target DAC register, determined by the decoding of address Bits A1 and A0. For AD5544, Table 5, Table 7, Table 9, and Figure 4 define the characteristics of the software serial interface. For AD5554, Table 6, Table 8, Table 9, and Figure 5 define the characteristics of the software serial interface. Figure 29 and Figure 30 show the equivalent logic interface for the key digital control pins for the AD5544. AD5554 has a similar configuration, except it has 14 data bits. Two additional pins, $\overline{RS}$ and MSB, provide hardware control over the preset function and DAC register loading.
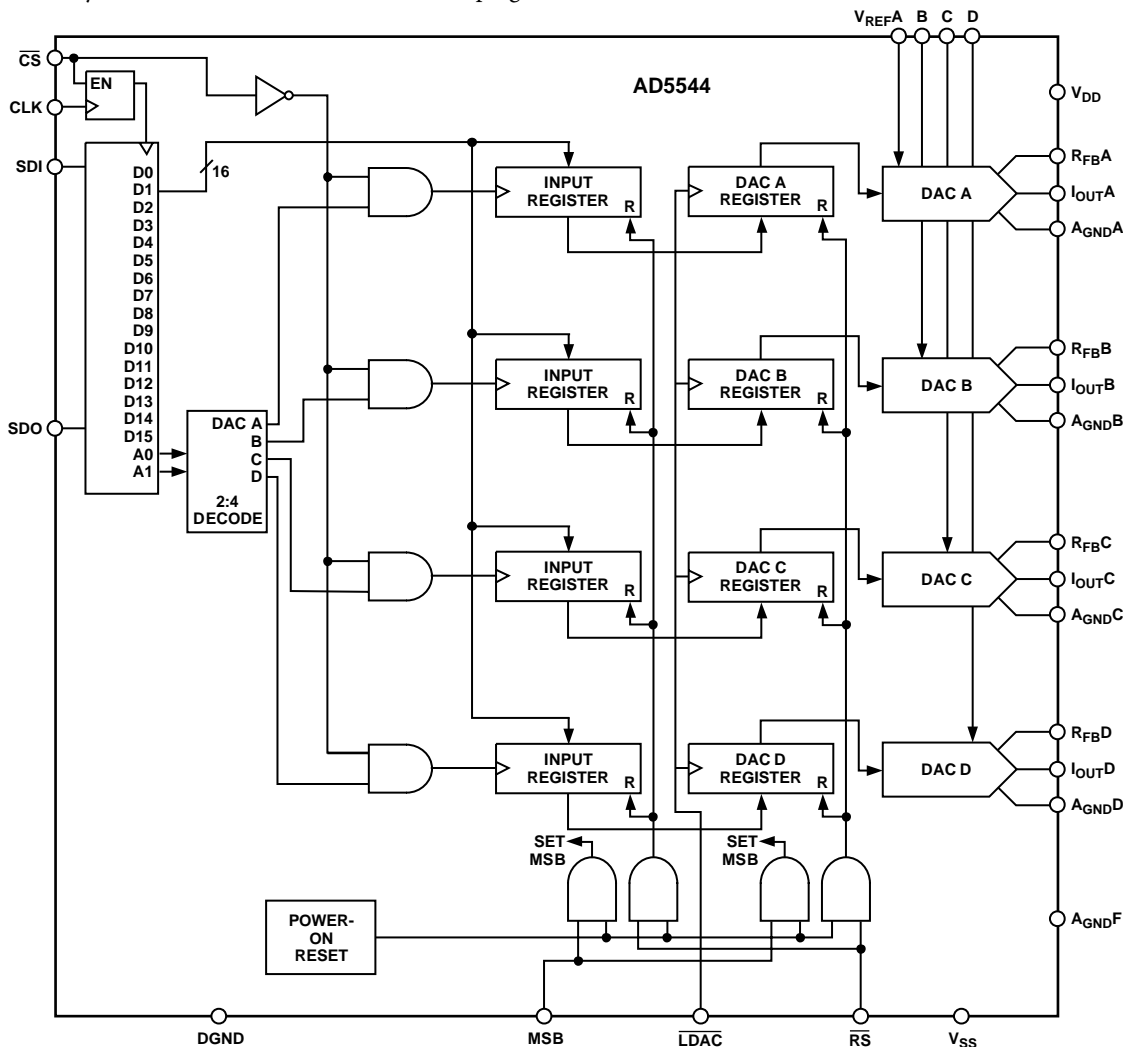

Figure 29. System Level Digital Interfacing

If these functions are not needed, the $\overline{RS}$ pin can be tied to logic high. The asynchronous input $\overline{RS}$ pin forces all input and DAC registers to either the zero-code state (MSB = 0) or the half-scale state (MSB = 1).
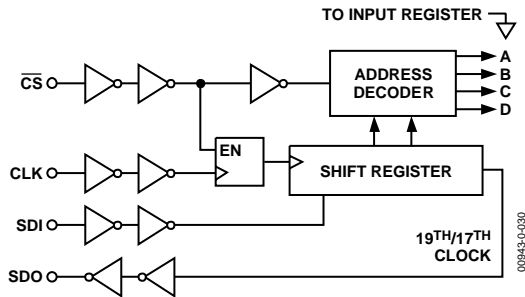

Figure 30. AD5544/AD5554 Equivalent Logic Interface

POWER ON RESET

When the V_{DD} power supply is turned on, an internal reset strobe forces all the input and DAC registers to the zero-code state or half-scale state, depending on the MSB pin voltage. The V_{DD} power supply should have a smooth positive ramp without drooping in order to have consistent results, especially in the region of V_{DD} = 1.5 V to 2.3 V. The V_{SS} supply has no effect on the power-on reset performance. The DAC register data will stay at a zero or half-scale setting until a valid serial register data load takes place.

ESD Protection Circuits

All logic-input pins contain back-biased ESD protection Zeners connected to ground (D_{GND}) and V_{DD}, as shown in Figure 31.
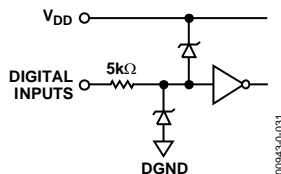

Figure 31. Equivalent ESD Production Circuits

Power Supply Sequence

As standard practice, it is recommended to power V_{DD}, V_{SS}, and ground prior to any reference. The ideal power up sequence is $A_{GND}X$, D_{GND}, V_{DD}, V_{SS}, $V_{REF}X$, and digital inputs. A noncompliance power up sequence may elevate the reference current, but the devices resume normal operation once V_{DD} and V_{SS} are powered-up.

Layout and Power Supply Bypassing

It is good practice to employ a compact, minimum-lead length layout design. The leads to the input should be as direct as possible with a minimum conductor length. Ground paths should have low resistance and low inductance.

Similarly, it is good practice to bypass the power supplies with quality capacitors for optimum stability. Supply leads to the device should be bypassed with 0.01 μF to 0.1 μF disc or chip ceramic capacitors. Low-ESR 1 μF to 10 μF tantalum or

electrolytic capacitors should also be applied at V_{DD} to minimize any transient disturbance and filter any low frequency ripple (see Figure 32). Users should not apply switching regulators for V_{DD} due to the power supply rejection ratio degradation over frequency.
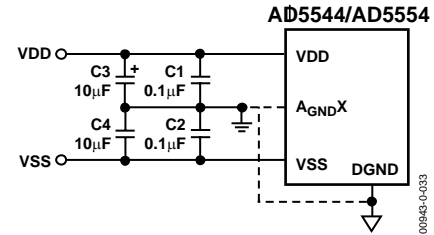

Figure 32. Power Supply Bypassing and Grounding Connection

Grounding

The DGND and AGNDX pins of the AD5544/AD5554 refer as digital and analog ground references. To minimize the digital ground bounce, the DGND terminal should be joined remotely at a single point to the analog ground plane (see Figure 32).
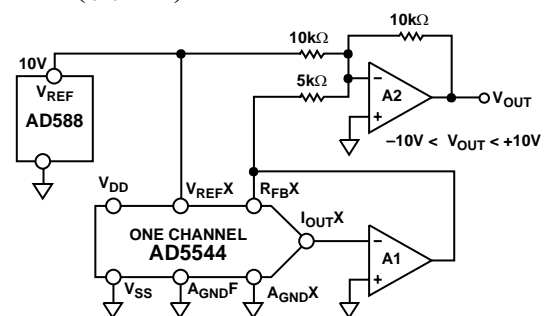
APPLICATIONS

The AD5544/AD5554 are inherently 2-quadrant multiplying D/A converters. That is, they can be easily set up for unipolar output operation. The full-scale output polarity is the inverse of the reference-input voltage.

In some applications it may be necessary to generate the full 4-quadrant multiplying capability or a bipolar output swing. This is easily accomplished using an additional external amplifier (A2) configured as a summing amplifier (see Figure 33). In this circuit the first and second amplifiers (A1 and A2) provide a total gain of 2 which increases the output voltage span to 20 V. Biasing the external amplifier with a 10 V offset from the reference voltage results in a full 4-quadrant multiplying circuit. The transfer equation of this circuit shows that both negative and positive output voltages are created as the input data (D) is incremented from code zero (V_{OUT} = −10 V) to midscale (V_{OUT} = 0 V) to full-scale (V_{OUT} = 10 V).

$$V_{OUT} \left(\frac{D}{32768} - 1 \right) \times - V_{REF} \ (For\ AD5544) \qquad (3)$$

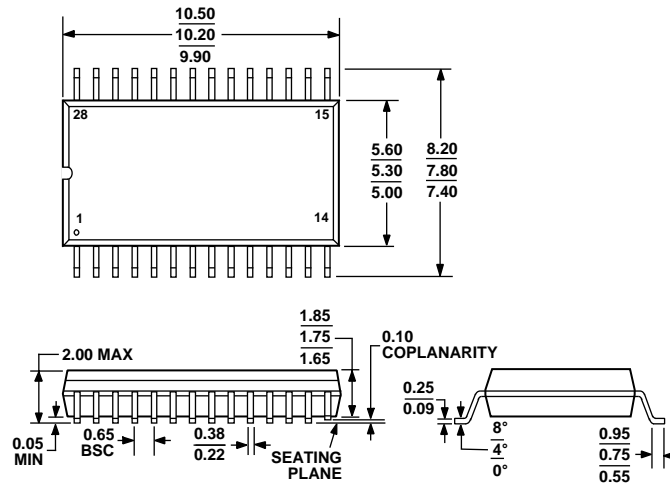$$V_{OUT} \left(\frac{D}{8192} - 1 \right) \times - V_{REF} \ (For\ AD5554) \qquad (4)$$

DIGITAL INTERFACE CONNECTIONS
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Figure 33. Four-Quadrant Multiplying Application Circuit

OUTLINE DIMENSIONS

COMPLIANT TO JEDEC STANDARDS MO-150AH

Figure 34. 28-Lead SSOP
(RS-28)
Dimensions Shown in Inches and (Millimeters)

ORDERING GUIDE

Model	RES Bit	INL LSB	DNL LSB	Temperature Range	Package Description	Package Option
AD5544ARS	16	±4	±1.5	−40°C to +85°C	SSOP-28	RS-28
AD5554BRS	14	±1	±1	−40°C to +85°C	SSOP-28	RS-28
AD5544EVAL					Evaluation Board	

NOTES

NOTES

**ANALOG
DEVICES**

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